ABSTRACT

Provided is a laser process device used in laser lift off processing for separating a thin film from a substrate. The laser process device includes a laser beam light source, an optical system, a stage, and a suction unit. The laser beam light source is configured to emit a laser beam. The optical system is configured to form a shape and energy profile of a laser beam emitted from the laser beam light source. A processing object is positioned on the stage and is processed through radiating the laser beam formed by the optical system thereon. The suction unit is disposed in a travel path of the laser beam formed by the optical system to transmit the laser beam therethrough, and is configured to suction by-products generated during processing of the processing object.